



Form PTO-1449

U.S. Application No.: 10/725,933

Attorney Docket No.: HK9225US (formerly 25857)

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INFORMATION DISCLOSURE CITATION

In re application of: Yang et al.

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Serial No.: 10/725,933

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Examiner: David A. Zarneke

For: FAN OUT TYPE WAFER LEVEL PACKAGE STRUCTURE AND METHOD OF THE SAME

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Foreign Patent Documents

Examiner Initials	Document Number	Country	Date of Publication	Class	Translation (Yes/No)
DAZ	177,766	Taiwan	09/05/2003	H01L23/02	Yes
DAZ	Abstract of Taiwan Patent Publication No. TW 531854B, published 05/11/2003.				

Examiner:

Date Considered:

/David Zarneke/

12/03/2006

****Examiner:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.